TEXAS INSTRUMENTS

MSP430 Application Report Book (SLAA024)

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ABSTRACT

This application book is a collection of many different application reports, application examples, and code examples for the MSP430 family of ultra-low-power microcontrollers.

Chapters

1. **MSP430 Microcontroller Family**
2. **Analog-to-Digital Converters**
3. **Hardware Applications**
4. **Application Examples**
5. **Software Applications**
6. **On-Chip Peripherals**
7. **Hints and Recommendations**
8. **Architecture and Instruction Set**
9. **CPU Registers**

Because of the length of this book, it may be downloaded by individual chapters at http://www.ti.com/sc/docs/products/micro/msp430/docs.htm.

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